

2017 SCHEDULE OF HIR WORKSHOPS

1. [EuroSIME](#) Dresden, Germany 4/6
2. [ICEP 2017](#) (JIEP) Yamagata Japan 4/19-22
3. [ECTC](#) Orlando, FL, USA 5/30-6/04
4. JIC (Jisso International Council) Spring Meeting 6/12
5. [NordPac](#) Gothenburg, Sweden 6/18-20
6. Palo Alto Workshop before SEMICON WEST, Palo Alto, CA, USA 7/9
7. [SEMICON WEST](#) San Francisco, CA USA 7/10
8. [InterPACK](#) (ASME) San Francisco, CA, USA 8/29-9/1
9. [ELECTRONICS PACKAGING SYMPOSIUM](#) , Niskayuna NY, USA 9/19-20
10. [IEEE PHOTONICS CONFERENCE](#) Lake Buena Vista, FL, USA, 10/1-5
11. HIR Workshop in association with [AIM Photonics Fall 2017 Meeting](#), Albany, NY 10/10-12
12. [IMPACT](#) Taipei, Taiwan 10/25-26
13. First Annual Heterogeneous Integration Workshop at UCLA 11/1
14. [ICSJ](#) Kyoto, Japan 11/20-22
15. [EPTC](#) Singapore 12/3-5
16. [IEDM](#) San Francisco, CA USA 12/3
17. [SEMICON](#) Japan at Tokyo Big Sight 12/13
18. Asia Workshops
 - A. [ICEPT](#), Harbin China 8/17
 - B. Tokyo workshop with CPMT Japan, JIEPS & SEMI Japan 8/10
 - C. ITRI Hsinchu, Taiwan 8/11
 - D. Hong Kong Workshop 8/14